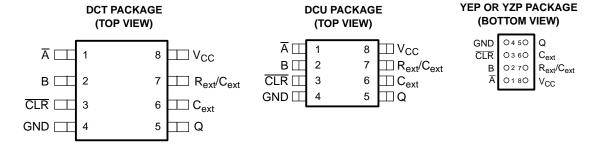
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#### **FEATURES**

- Available in the Texas Instruments
   NanoStar<sup>™</sup> and NanoFree<sup>™</sup> Packages
- Supports 5-V V<sub>CC</sub> Operation
- Inputs Accept Voltages to 5.5 V
- Max t<sub>pd</sub> of 8 ns at 3.3 V
- Supports Mixed-Mode Voltage Operation on All Ports
- Schmitt-Trigger Circuitry on A and B Inputs for Slow Input Transition Rates
- Edge Triggered From Active-High or Active-Low Gated Logic Inputs

- Retriggerable for Very Long Output Pulses, up to 100% Duty Cycle
- Overriding Clear Terminates Output Pulse
- Glitch-Free Power-Up Reset on Outputs
- I<sub>off</sub> Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)



See mechanical drawings for dimensions.

#### DESCRIPTION/ORDERING INFORMATION

The SN74LVC1G123 is a single retriggerable monostable multivibrator designed for 1.65-V to 5.5-V  $V_{CC}$  operation.

This monostable multivibrator features output pulse-duration control by three methods. In the first method, the  $\overline{A}$  input is low, and the  $\overline{B}$  input goes high. In the second method, the  $\overline{B}$  input is high, and the  $\overline{A}$  input goes low. In the third method, the  $\overline{A}$  input is low, the  $\overline{B}$  input is high, and the clear ( $\overline{CLR}$ ) input goes high.

#### ORDERING INFORMATION

T <sub>A</sub>	PACKAGE <sup>(1)</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING(2)
	NanoStar™ – WCSP (DSBGA) 0.23-mm Large Bump – YEP	Reel of 3000	SN74LVC1G123YEPR	Do
	NanoFree <sup>™</sup> – WCSP (DSBGA) 0.23-mm Large Bump – YZP (Pb-free)	17661 01 3000	SN74LVC1G123YZPR	D8_
–40°C to 85°C	SSOP - DCT	Reel of 3000	SN74LVC1G123DCTR	C23
	330F = DC1	Reel of 250	SN74LVC1G123DCTT	023_
	VSSOP – DCU	Reel of 3000	SN74LVC1G123DCUR	Coo
	V330F - DC0	Reel of 250 SN74LVC1G123DCUT C23_		C23_

<sup>(1)</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

<sup>(2)</sup> DCT: The actual top-side marking has three additional characters that designate the year, month, and assembly/test site.

DCU: The actual top-side marking has one additional character that designates the assembly/test site.

YEP/YZP: The actual top-side marking has three preceding characters to denote year, month, and sequence code, and one following character to designate the assembly/test site. Pin 1 identifier indicates solder-bump composition (1 = SnPb, ● = Pb-free).



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

NanoStar, NanoFree are trademarks of Texas Instruments.

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## **DECSCRIPTION/ORDERING INFORMATION (CONTINUED)**

The output pulse duration is programmed by selecting external resistance and capacitance values. The external timing capacitor must be connected between  $C_{ext}$  and  $R_{ext}/C_{ext}$  (positive) and an external resistor connected between  $R_{ext}/C_{ext}$  and  $V_{CC}$ . To obtain variable pulse durations, connect an external variable resistance between  $R_{ext}/C_{ext}$  and  $V_{CC}$ . The output pulse duration also can be reduced by taking  $\overline{CLR}$  low.

Pulse triggering occurs at a particular voltage level and is not directly related to the transition time of the input pulse. The  $\overline{A}$  and B inputs have Schmitt triggers with sufficient hysteresis to handle slow input transition rates with jitter-free triggering at the outputs.

Once triggered, the basic pulse duration can be extended by retriggering the gated low-level-active  $(\overline{A})$  or high-level-active (B) input. Pulse duration can be reduced by taking  $\overline{CLR}$  low.  $\overline{CLR}$  can be used to override  $\overline{A}$  or B inputs. The input/output timing diagram illustrates pulse control by retriggering the inputs and early clearing.

This device is fully specified for partial-power-down applications using  $I_{off}$ . The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

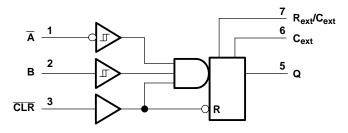
NanoStar<sup>™</sup> and NanoFree<sup>™</sup> package technology is a major breakthrough in IC packaging concepts, using the die as the package.

#### **FUNCTION TABLE**

	INPUTS	OUTPUTS	
CLR	Ā	В	Q
L	Χ	Χ	L
X	Н	Χ	L <sup>(1)</sup>
X	Χ	L	L <sup>(1)</sup>
Н	L	$\uparrow$	Л
Н	$\downarrow$	Н	Л
1	L	Н	Л

(1) These outputs are based on the assumption that the indicated steady-state conditions at the A and B inputs have been set up long enough to complete any pulse started before the setup.

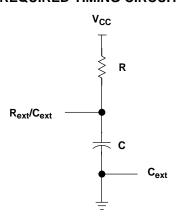
#### **LOGIC DIAGRAM (POSITIVE LOGIC)**



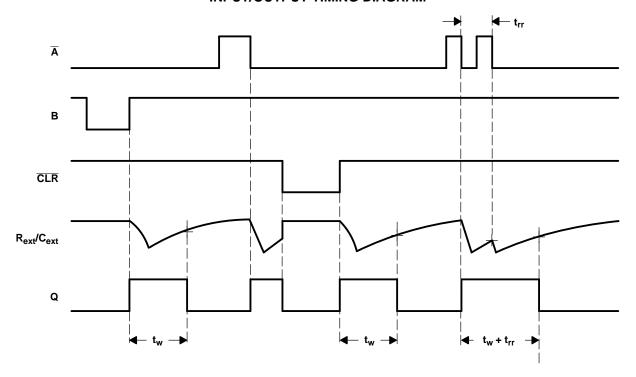


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## **REQUIRED TIMING CIRCUIT**



## INPUT/OUTPUT TIMING DIAGRAM



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## **Absolute Maximum Ratings**(1)

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
$V_{CC}$	Supply voltage range		-0.5	6.5	V
VI	Input voltage range <sup>(2)</sup>	-0.5	6.5	V	
Vo	Voltage range applied to any output in the high-impedance or power-off state <sup>(2)</sup>				V
Vo	Voltage range applied to any output in the	high or low state <sup>(2)(3)</sup>	-0.5	V <sub>CC</sub> + 0.5	V
I <sub>IK</sub>	Input clamp current	V <sub>I</sub> < 0		-50	mA
I <sub>OK</sub>	Output clamp current V <sub>O</sub> < 0			-50	mA
Io	Continuous output current			±50	mA
	Continuous current through V <sub>CC</sub> or GND			±100	mA
		DCT package		220	
$\theta_{JA}$	Package thermal impedance (4)	DCU package		227	°C/W
		YEP/YZP package		102	
T <sub>stg</sub>	Storage temperature range	-65	150	°C	

<sup>(1)</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

The value of V<sub>CC</sub> is provided in the recommended operating conditions table.

<sup>(4)</sup> The package thermal impedance is calculated in accordance with JESD 51-7.

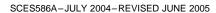


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# Recommended Operating Conditions<sup>(1)</sup>

			MIN	MAX	UNIT
V	Cumply voltage	Operating	1.65	5.5	V
$V_{CC}$	Supply voltage	Data retention only	1.5		V
		V <sub>CC</sub> = 1.65 V to 1.95 V	0.65 × V <sub>CC</sub>		
\	High level innertualtane	V <sub>CC</sub> = 2.3 V to 2.7 V	1.7		V
$V_{IH}$	High-level input voltage	V <sub>CC</sub> = 3 V to 3.6 V	2		V
		V <sub>CC</sub> = 4.5 V to 5.5 V	0.7 × V <sub>CC</sub>		
		V <sub>CC</sub> = 1.65 V to 1.95 V		0.35 × V <sub>CC</sub>	
V	Low lovel input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		0.7	V
$V_{IL}$	Low-level input voltage	V <sub>CC</sub> = 3 V to 3.6 V		0.8	V
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		$0.3 \times V_{CC}$	
VI	Input voltage		0	5.5	V
Vo	Output voltage		0	$V_{CC}$	V
		V <sub>CC</sub> = 1.65 V		-4	
		V <sub>CC</sub> = 2.3 V		-8	
$I_{OH}$	High-level output current	V <sub>CC</sub> = 3 V		-16	mA
		V <sub>CC</sub> = 3 V		-24	
		V <sub>CC</sub> = 4.5 V		-32	
		V <sub>CC</sub> = 1.65 V		4	
		V <sub>CC</sub> = 2.3 V		8	
$I_{OL}$	Low-level output current	V 2V		16	mA
		V <sub>CC</sub> = 3 V		24	
		V <sub>CC</sub> = 4.5 V		32	
D (2)	External timing registers as	V <sub>CC</sub> = 2 V	5 k		0
R <sub>ext</sub> <sup>(2)</sup>	External timing resistance	V <sub>CC</sub> ≥ 3 V	1 k		Ω
T <sub>A</sub>	Operating free-air temperature		-40	85	°C

All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.  $R_{ext}/C_{ext}$  is an I/O and must not be connected directly to GND or  $V_{CC}$ . (1)





#### **Electrical Characteristics**

over recommended operating free-air temperature range (unless otherwise noted)

Р	ARAMETER	TES	T CONDITIONS	V <sub>CC</sub>	MIN	TYP <sup>(1)</sup>	MAX	UNIT
		$I_{OH} = -100 \mu A$		1.65 V to 5.5 V	V <sub>CC</sub> - 0.1			
		$I_{OH} = -4 \text{ mA}$		1.65 V	1.2			
\/		$I_{OH} = -8 \text{ mA}$		2.3 V	1.9			V
V <sub>OH</sub>		$I_{OH} = -16 \text{ mA}$		3 V	2.4			V
		$I_{OH} = -24 \text{ mA}$		3 V	2.3			
		$I_{OH} = -32 \text{ mA}$		4.5 V	3.8			
		I <sub>OL</sub> = 100 μA		1.65 V to 5.5 V			0.1	
		I <sub>OL</sub> = 4 mA		1.65 V			0.45	
.,		I <sub>OL</sub> = 8 mA		2.3 V			0.3	V
$V_{OL}$		I <sub>OL</sub> = 16 mA		3 V			0.4	V
		I <sub>OL</sub> = 24 mA		3 V			0.55	
		I <sub>OL</sub> = 32 mA		4.5 V			0.55	
	R <sub>ext</sub> /C <sub>ext</sub> (2)	B = GND,	$\overline{A} = \overline{CLR} = V_{CC}$	4.05.7/+- 5.5.7/			±0.25	^
I	A, B, CLR	V <sub>I</sub> = 5.5 V or GND		1.65 V to 5.5 V			±1	μΑ
I <sub>off</sub>	Ā, B, Q, CLR	$V_1$ or $V_0 = 5.5 \text{ V}$		0			±10	μΑ
I <sub>CC</sub>	Quiescent	$V_I = V_{CC}$ or GND,	I <sub>O</sub> = 0	5.5 V			20	μΑ
				1.65 V			165	
				2.3 V			220	
I <sub>CC</sub>	Active state	$V_I = V_{CC}$ or GND,	$R_{ext}/C_{ext} = 0.5 V_{CC}$	3 V			280	μΑ
				4.5 V			650	
				5.5 V			975	
C <sub>i</sub>		$V_I = V_{CC}$ or GND		3.3 V		3		pF

### **Timing Requirements**

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

	PARAMETER		TEST C	TEST CONDITIONS		V <sub>CC</sub> = 1.8 V ± 0.15 V		$V_{CC}$ = 2.5 V $\pm$ 0.2 V		V <sub>CC</sub> = 3.3 V ± 0.3 V		V <sub>CC</sub> = 5 V ± 0.5 V	
					MIN	TYP	MIN	TYP	MIN	TYP	MIN	TYP	
+ INI	Pulse duration	CLR			8		4		3		2.5		no
t <sub>w</sub> IN	Fuise duration	A or B trigger			8		4		3		2.5		ns
			D - 1 kO	C <sub>ext</sub> = 100 pF						5.5		4.5	ns
	Pulse retrigger time		$\kappa_{\rm ext} = 1  \kappa_{\rm S2}$	$C_{\text{ext}} = 100 \text{ pF}$ $C_{\text{ext}} = 100 \mu\text{F}$						1.4		1.1	μs
t <sub>rr</sub>	ir i dise retilgger time		D 510	$C_{\text{ext}}$ = 100 pF $C_{\text{ext}}$ = 100 $\mu$ F		75		45					ns
			$R_{\text{ext}} = 5 \text{ k}\Omega$	$C_{ext} = 100 \mu F$		1.8		1.4					μs

## **Switching Characteristics**

over recommended operating free-air temperature range,  $C_L = 15 \text{ pF}$  (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>C</sub>	<sub>C</sub> = 1.8 \ : 0.15 V	V	V <sub>CC</sub> = ± 0.2		V <sub>CC</sub> = ± 0.3		V <sub>CC</sub> = ± 0.5		UNIT
	(INPOT)	(001F01)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
	Ā or B		7	18.5	52	4	17	3	11.5	2	7.6	
t <sub>pd</sub>	CLR	Q	5	12.4	34	3	11.5	2	8	1.5	5.5	ns
	CLR trigger		7	17.4	54	4	15.5	3	10.5	2	7	

All typical values are at  $V_{CC}$  = 3.3 V,  $T_A$  = 25°C. This test is performed with the terminal in the off-state condition.



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## **Switching Characteristics**

over recommended operating free-air temperature range,  $C_L = 50 \text{ pF}$  (unless otherwise noted) (see Figure 2)

PARAMETER	FROM	то	TEST		<sub>C</sub> = 1.8 0.15 V		V <sub>CC</sub> = ± 0.	2.5 V 2 V	V <sub>CC</sub> = ± 0.	3.3 V 3 V	V <sub>CC</sub> = ± 0.		UNIT
PARAMETER	(INPUT)	(OUTPUT)	CONDITIONS	MIN	TYP <sup>(</sup>	MAX	MIN	MAX	MIN	MAX	MIN	MAX	UNII
	Ā or B			6	18.6	57	3	18.5	2	12.5	1.5	8.2	
t <sub>pd</sub>	CLR	Q		4	11.6	36.5	2	12.5	1.5	8.6	1.5	6	ns
	CLR trigger			5	17.3	59	2.5	17	2	11.5	1.5	7.5	
			$C_{\text{ext}} = 28 \text{ pF},$ $R_{\text{ext}} = 2 \text{ k}\Omega$		225	600	190	220	170	200	150	180	ns
t <sub>w</sub> OUT <sup>(2)</sup>		Q	$C_{\text{ext}} = 0.01 \mu\text{F},$ $R_{\text{ext}} = 10 \text{k}\Omega$		100	110	100	110	100	110	100	110	μs
			$C_{\text{ext}} = 0.1 \mu\text{F},$ $R_{\text{ext}} = 10 \text{k}\Omega$		1	1.1	1	1.1	1	1.1	1	1.1	ms

## **Operating Characteristics**

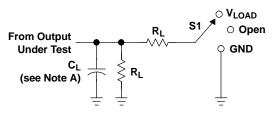
T<sub>A</sub> = 25°C

	PARAMETER	TEST CONDITIONS		V <sub>CC</sub> = 1.8 V TYP	V <sub>CC</sub> = 2.5 V TYP	V <sub>CC</sub> = 3.3 V TYP	V <sub>CC</sub> = 5 V TYP	UNIT
Cod	Power dissipation	$\overline{A} = low, B = high,$	$R_{ext} = 1 \text{ k}\Omega,$ No $C_{ext}$			35	37	pF
Cpd	capacitance	CLR = 10 MHz	$R_{ext} = 5 \text{ k}\Omega,$ No $C_{ext}$	41	40			þΓ

<sup>(1)</sup>  $T_A = 25^{\circ}C$ (2)  $t_w = Duration of pulse at Q output$ 



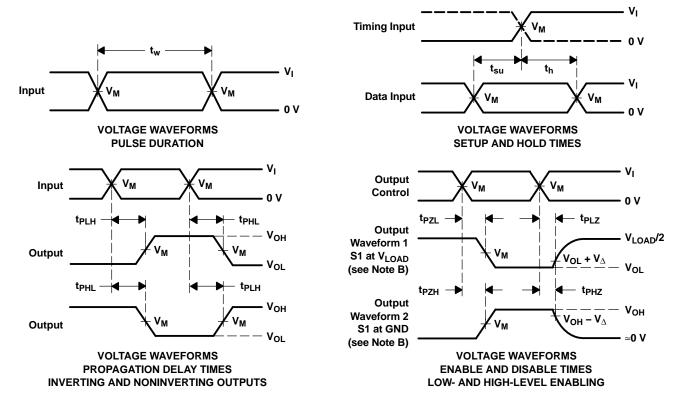
#### PARAMETER MEASUREMENT INFORMATION



TEST	S1
t <sub>PLH</sub> /t <sub>PHL</sub>	Open
t <sub>PLZ</sub> /t <sub>PZL</sub>	V <sub>LOAD</sub>
t <sub>PHZ</sub> /t <sub>PZH</sub>	GND

**LOAD CIRCUIT** 

v	INF	INPUTS		V	•		\ \ \
V <sub>CC</sub>	VI	t <sub>r</sub> /t <sub>f</sub>	V <sub>M</sub>	V <sub>LOAD</sub>	CL	R <sub>L</sub>	$V_{\Delta}$
1.8 V $\pm$ 0.15 V	V <sub>CC</sub>	≤2 ns	V <sub>CC</sub> /2	2×V <sub>CC</sub>	15 pF	<b>1 M</b> Ω	0.15 V
2.5 V $\pm$ 0.2 V	V <sub>CC</sub>	≤2 ns	V <sub>CC</sub> /2	2×V <sub>CC</sub>	15 pF	<b>1 M</b> Ω	0.15 V
3.3 V $\pm$ 0.3 V	3 V	≤2.5 ns	1.5 V	6 V	15 pF	<b>1 M</b> Ω	0.3 V
5 V ± 0.5 V	V <sub>CC</sub>	≤2.5 ns	V <sub>CC</sub> /2	2×V <sub>CC</sub>	15 pF	<b>1 M</b> Ω	0.3 V



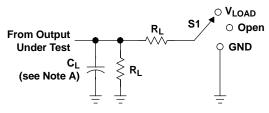
NOTES: A.  $C_L$  includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z<sub>O</sub> = 50 Ω.
- D. The outputs are measured one at a time, with one transition per measurement.
- E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
- F. t<sub>PZL</sub> and t<sub>PZH</sub> are the same as t<sub>en</sub>.
- G. t<sub>PLH</sub> and t<sub>PHL</sub> are the same as t<sub>pd</sub>.
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

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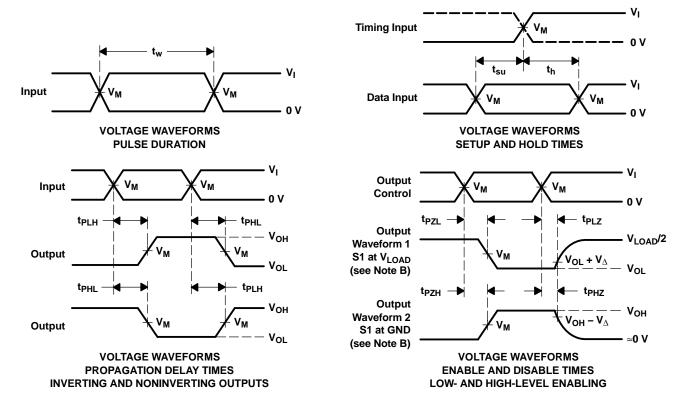
#### PARAMETER MEASUREMENT INFORMATION



TEST	<b>S</b> 1
t <sub>PLH</sub> /t <sub>PHL</sub>	Open
t <sub>PLZ</sub> /t <sub>PZL</sub>	$V_{LOAD}$
t <sub>PHZ</sub> /t <sub>PZH</sub>	GND

**LOAD CIRCUIT** 

.,	INPUTS		.,	.,		_	V
V <sub>CC</sub>	VI	t <sub>r</sub> /t <sub>f</sub>	V <sub>M</sub>	V <sub>LOAD</sub>	CL	$R_L$	$V_{\Delta}$
1.8 V $\pm$ 0.15 V	v <sub>cc</sub>	≤2 ns	V <sub>CC</sub> /2	2×V <sub>CC</sub>	30 pF	<b>1 k</b> Ω	0.15 V
2.5 V $\pm$ 0.2 V	$V_{CC}$	≤2 ns	V <sub>CC</sub> /2	2×V <sub>CC</sub>	30 pF	500 $\Omega$	0.15 V
3.3 V $\pm$ 0.3 V	3 V	≤2.5 ns	1.5 V	6 V	50 pF	500 $\Omega$	0.3 V
5 V $\pm$ 0.5 V	$v_{cc}$	≤2.5 ns	V <sub>CC</sub> /2	2×V <sub>CC</sub>	50 pF	500 $\Omega$	0.3 V



NOTES: A.  $C_L$  includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z<sub>O</sub> = 50 Ω.
- D. The outputs are measured one at a time, with one transition per measurement.
- E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
- F. t<sub>PZL</sub> and t<sub>PZH</sub> are the same as t<sub>en</sub>.
- G. t<sub>PLH</sub> and t<sub>PHL</sub> are the same as t<sub>pd</sub>.
- H. All parameters and waveforms are not applicable to all devices.

Figure 2. Load Circuit and Voltage Waveforms



### **APPLICATION INFORMATION**(1)

#### **OUTPUT PULSE DURATION**

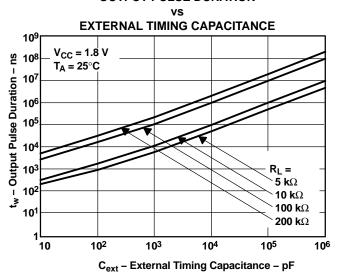


Figure 3.

### **OUTPUT PULSE DURATION**

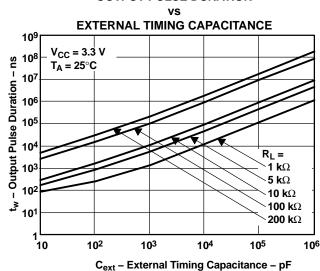


Figure 4.

(1) Operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied.



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## **OUTPUT PULSE DURATION**

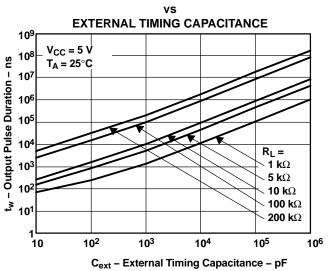


Figure 5.

## **OUTPUT PULSE DURATION CONSTANT**

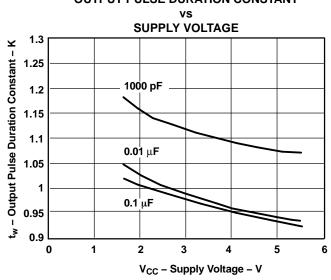
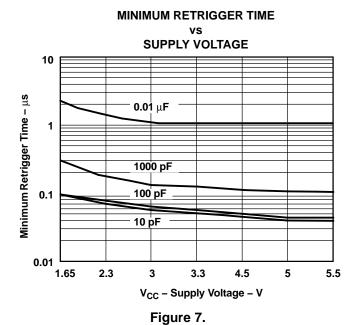


Figure 6.









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#### PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
74LVC1G123DCURE4	ACTIVE	US8	DCU	8	3000	Pb-Free (RoHS)	CU NIPDAU	Level-1-260C-UNLIM
74LVC1G123DCUTE4	ACTIVE	US8	DCU	8	250	Pb-Free (RoHS)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1G123DCTR	ACTIVE	SM8	DCT	8	3000	Pb-Free (RoHS)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1G123DCTT	ACTIVE	SM8	DCT	8	250	Pb-Free (RoHS)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1G123DCUR	ACTIVE	US8	DCU	8	3000	Pb-Free (RoHS)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1G123DCUT	ACTIVE	US8	DCU	8	250	Pb-Free (RoHS)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1G123YEPR	ACTIVE	WCSP	YEP	8	3000	TBD	SNPB	Level-1-260C-UNLIM
SN74LVC1G123YZPR	ACTIVE	WCSP	YZP	8	3000	Pb-Free (RoHS)	SNAGCU	Level-1-260C-UNLIM

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

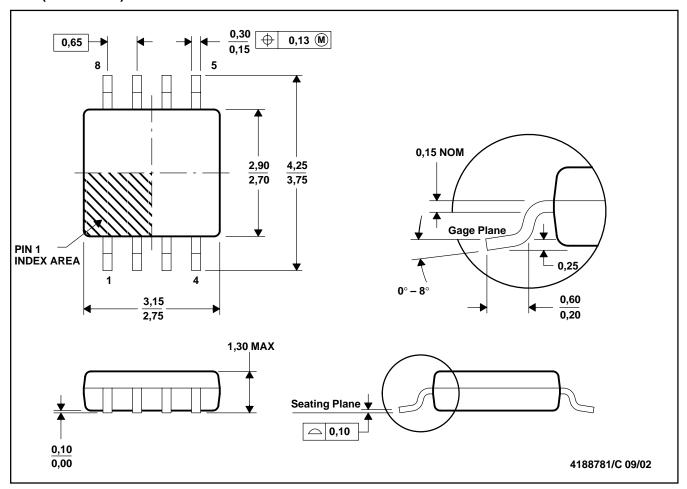
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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## DCT (R-PDSO-G8)

### PLASTIC SMALL-OUTLINE PACKAGE

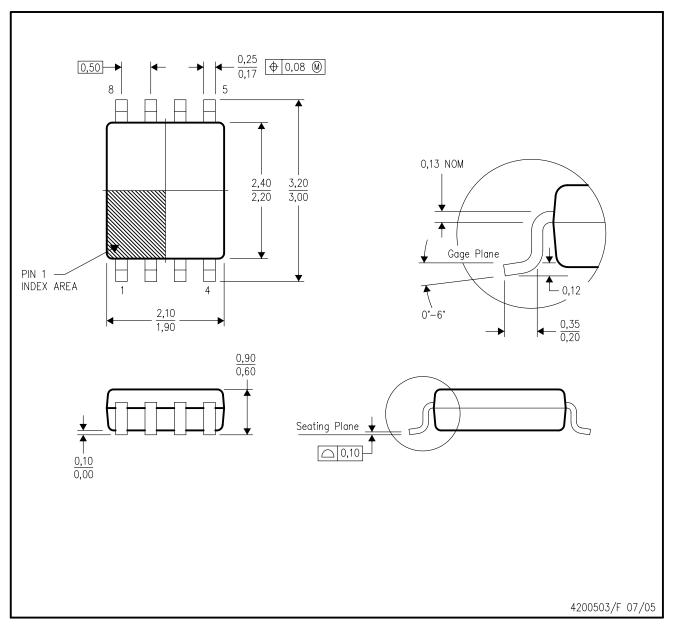


NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion
- D. Falls within JEDEC MO-187 variation DA.

# DCU (R-PDSO-G8)

# PLASTIC SMALL-OUTLINE PACKAGE (DIE DOWN)



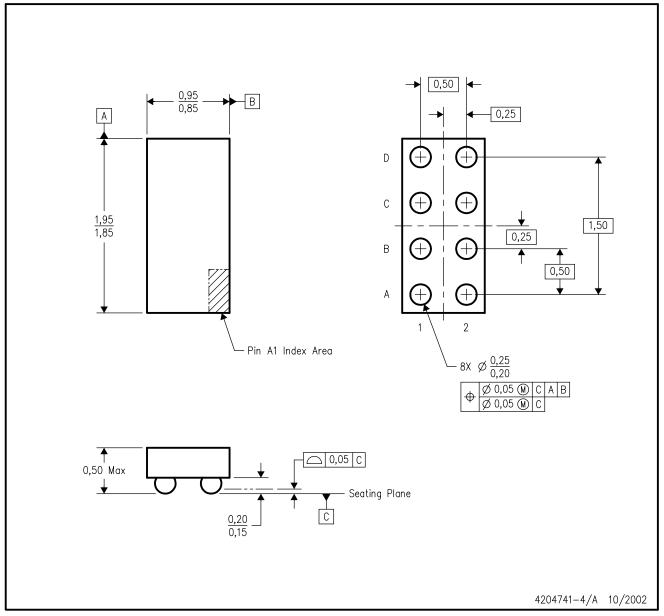
NOTES:

- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
  - D. Falls within JEDEC MO-187 variation CA.



# YZP (R-XBGA-N8)

## DIE-SIZE BALL GRID ARRAY



NOTES: A. All linear dimensions are in millimeters.

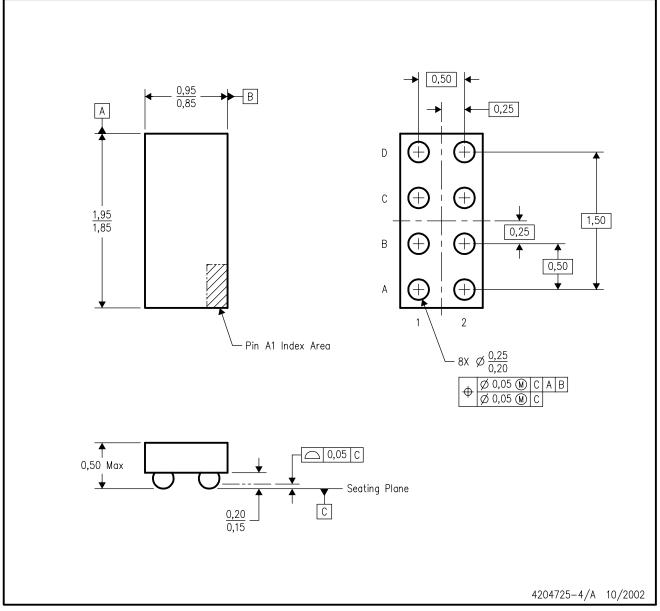
- B. This drawing is subject to change without notice.
- C. NanoFree  $^{\text{TM}}$  package configuration.
- D. This package is lead-free. Refer to the 8 YEP package (drawing 4204725) for tin-lead (SnPb).

NanoFree is a trademark of Texas Instruments.



# YEP (R-XBGA-N8)

## DIE-SIZE BALL GRID ARRAY



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. NanoStar  $\mathbf{M}$  package configuration.
- D. This package is tin-lead (SnPb). Refer to the 8 YZP package (drawing 4204741) for lead-free.

NanoStar is a trademark of Texas Instruments.



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Mailing Address: Texas Instruments

Post Office Box 655303 Dallas, Texas 75265

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